



SMD Comm X8G HT150C Flex, Ceramic, 130 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

130 pF

Time is 1000 Hours

100 GOhms

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
В	0.6mm +/-0.25mm

4mm	Measurement Condition	1 MHz 1.0Vrms
3mm	Tolerance	1%
0.20mm	Voltage DC	250 VDC
	Dielectric Withstanding Voltage	625 VDC
.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
n, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

**Specifications** 

Insulation Resistance

Capacitance

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

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